

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

TPCF8301

Notebook PC Applications
 Portable Equipment Applications

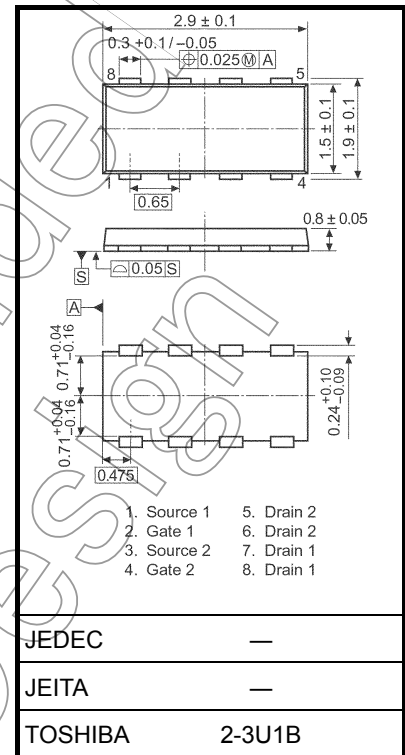
- Low drain-source ON resistance: $R_{DS(ON)} = 72 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 4.7 \text{ S}$ (typ.)
- Low leakage current: $I_{DSS} = -10 \mu\text{A}$ (max) ($V_{DS} = -20 \text{ V}$)
- Enhancement model: $V_{th} = -0.5 \text{ to } -1.2 \text{ V}$
 ($V_{DS} = -10 \text{ V}$, $I_D = -200 \mu\text{A}$)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	-20	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	-20	V
Gate-source voltage		V_{GSS}	± 8	V
Drain current	DC (Note 1)	I_D	-2.7	A
	Pulse (Note 1)	I_{DP}	-10.8	
Drain power dissipation ($t = 5 \text{ s}$) (Note 2a)	Single-device operation (Note 3a)	$P_D(1)$	1.35	W
	Single-device value at dual operation (Note 3b)	$P_D(2)$	1.12	
Drain power dissipation ($t = 5 \text{ s}$) (Note 2b)	Single-device operation (Note 3a)	$P_D(1)$	0.53	W
	Single-device value at dual operation (Note 3b)	$P_D(2)$	0.33	
Single pulse avalanche energy (Note 4)		E_{AS}	1,2	mJ
Avalanche current		I_{AR}	-1.35	A
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E_{AR}	0.11	mJ
Channel temperature		T_{ch}	150	$^\circ\text{C}$
Storage temperature range		T_{stg}	-55~150	$^\circ\text{C}$

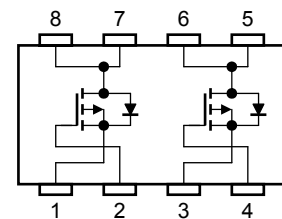
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Unit: mm



Weight: 0.011 g (typ.)

Circuit Configuration



Thermal Characteristics

Characteristics		Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	92.6	°C/W
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	111.6	
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	235.8	°C/W
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	378.8	

Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5) and (Note 6): See the next page.

This transistor is an electrostatic-sensitive device. Please handle with caution.

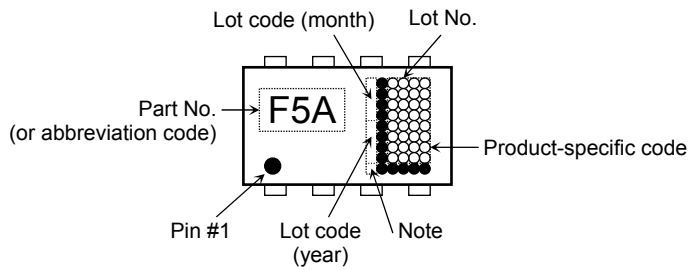
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±8 V, V _{DS} = 0 V	—	—	±10	μA
Drain cut-off current		I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V	—	—	-10	μA
Drain-source breakdown voltage		V _{(BR) DSS}	I _D = -10 mA, V _{GS} = 0 V	-20	—	—	V
		V _{(BR) DSX}	I _D = -10 mA, V _{GS} = 8 V	-12	—	—	
Gate threshold voltage		V _{th}	V _{DS} = -10 V, I _D = -200 μA	-0.5	—	-1.2	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = -1.8 V, I _D = -0.7 A	—	215	300	mΩ
		R _{DS (ON)}	V _{GS} = -2.5 V, I _D = -1.4 A	—	110	160	
		R _{DS (ON)}	V _{GS} = -4.5 V, I _D = -1.4 A	—	72	110	
Forward transfer admittance		Y _{fs1}	V _{DS} = -10 V, I _D = -1.4 A	2.4	4.7	—	S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	—	470	—	pF
Reverse transfer capacitance		C _{rss}		—	70	—	
Output capacitance		C _{oss}		—	80	—	
Switching time	Rise time	t _r		—	5	—	ns
	Turn-on time	t _{on}		—	9	—	
	Fall time	t _f		—	8	—	
	Turn-off time	t _{off}		Duty ≤ 1%, t _w = 10 μs	—	26	
Total gate charge (gate-source plus gate-drain)		Q _g	V _{DD} ≈ -16 V, V _{GS} = -5 V, I _D = -2.7 A	—	6	—	nC
Gate-source charge		Q _{gs}		—	4	—	
Gate-drain ("miller") charge		Q _{gd}		—	2	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	—	—	—	-10.8	A
Forward voltage (diode)		V _{DSF}	I _{DR} = -2.7 A, V _{GS} = 0 V	—	—	1.2	V

Marking (Note 6)



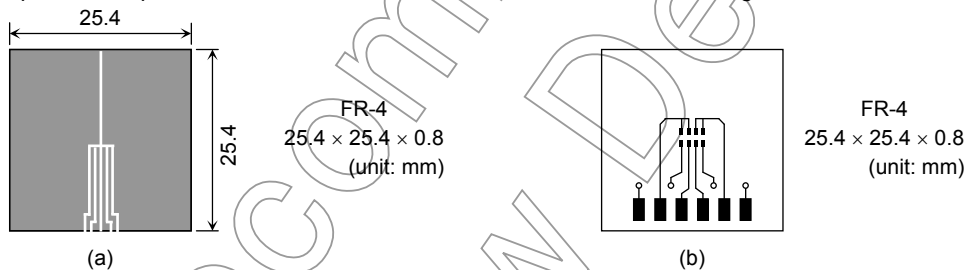
Note: A dot marking for identifying the indication of product Labels.
 Without a dot: [[Pb]]/INCLUDES > MCV
 With a dot: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.
 The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)

Note 3: a) The power dissipation and thermal resistance values are shown for a single device



(During single-device operation, power is only applied to one device.)

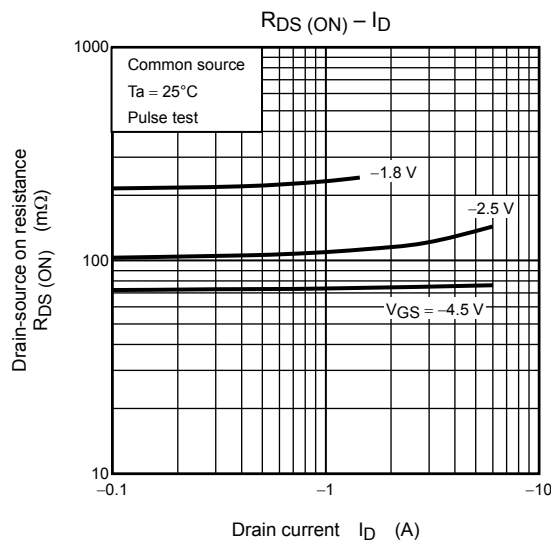
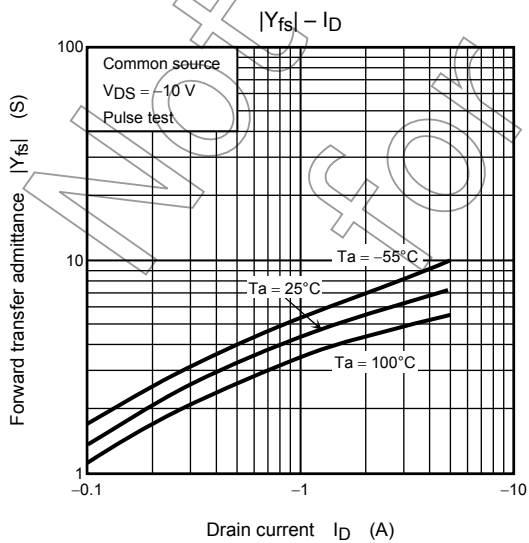
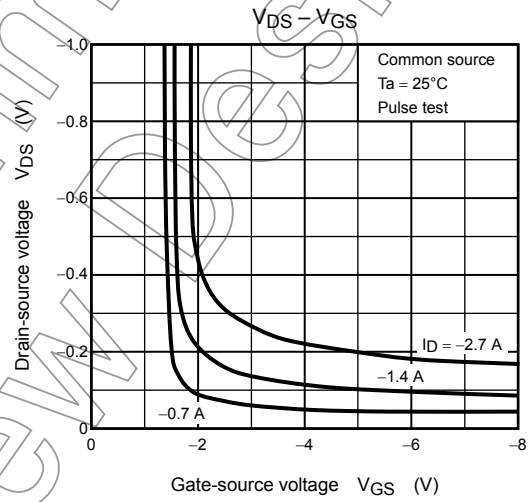
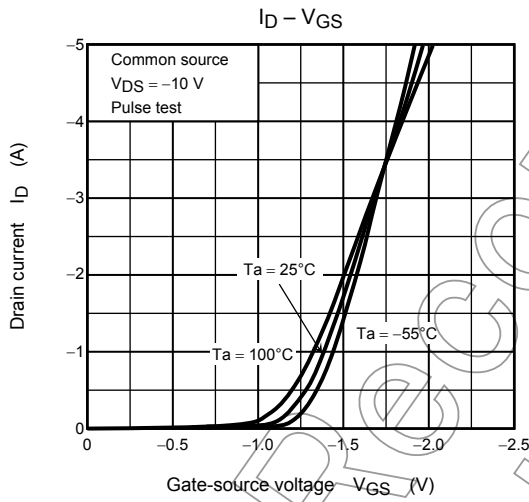
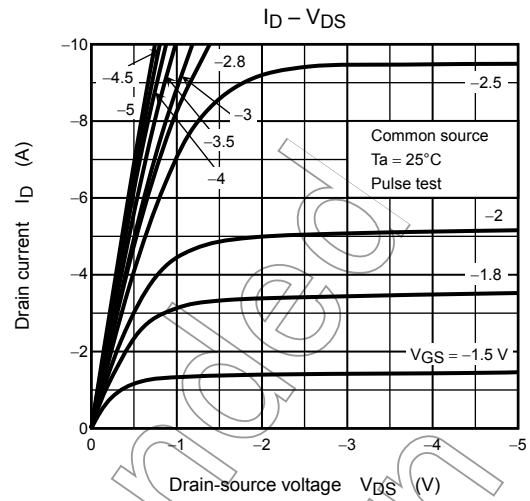
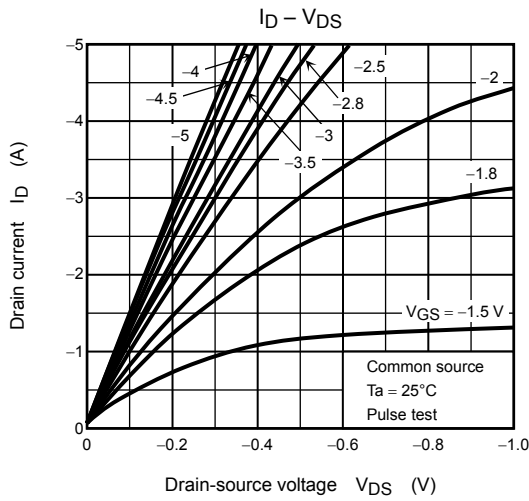
b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

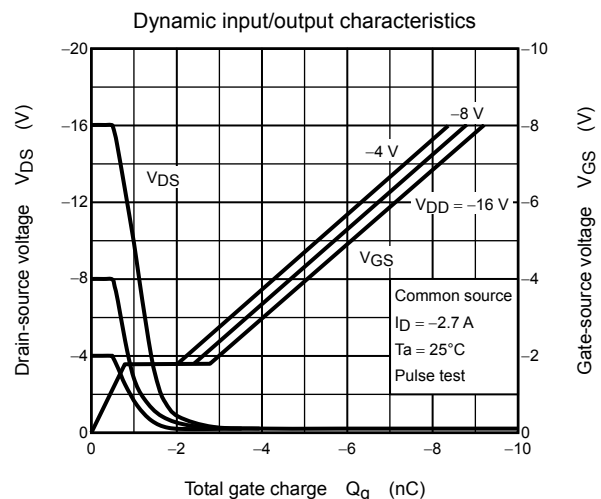
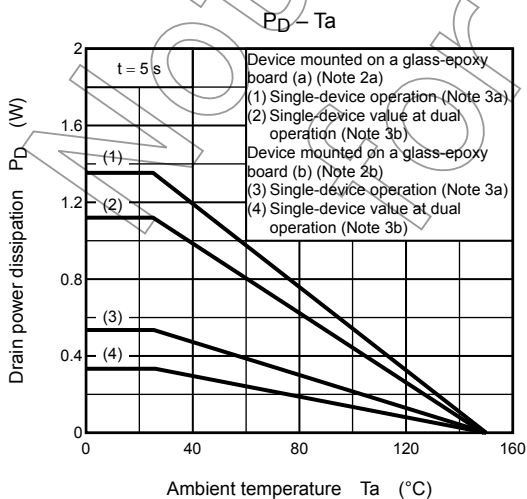
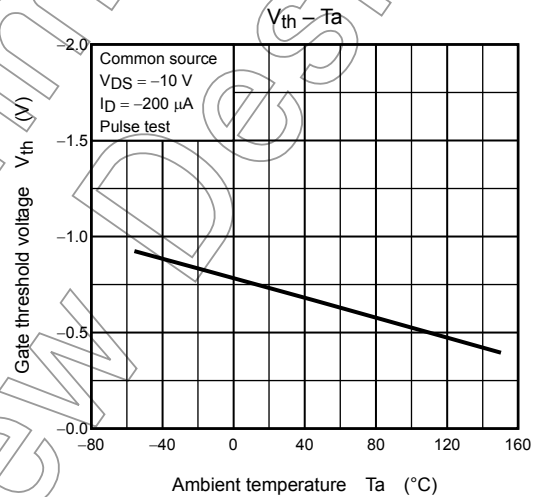
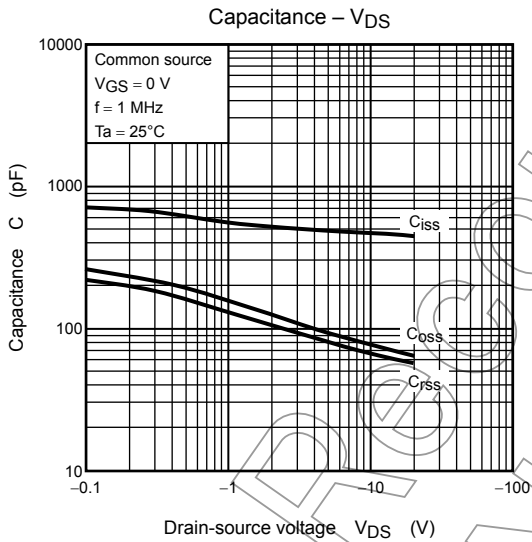
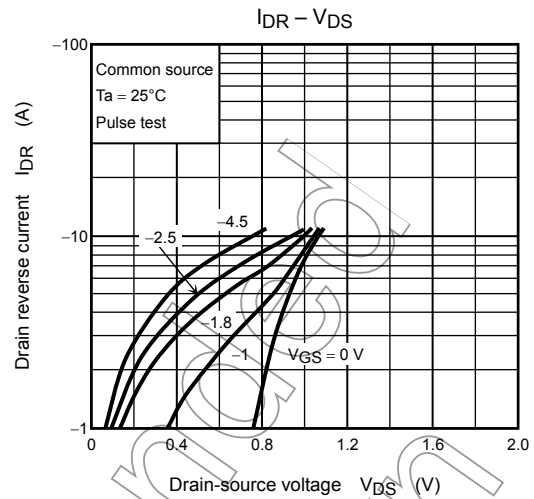
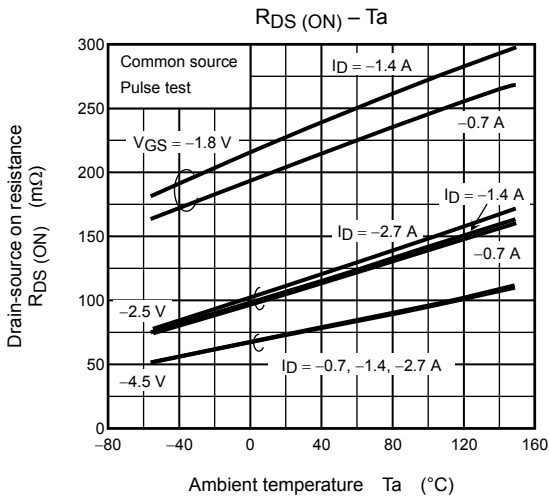
Note 4: $V_{DD} = -16\text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.5\text{ mH}$, $R_G = 25\ \Omega$, $I_{AR} = -1.35\text{ A}$

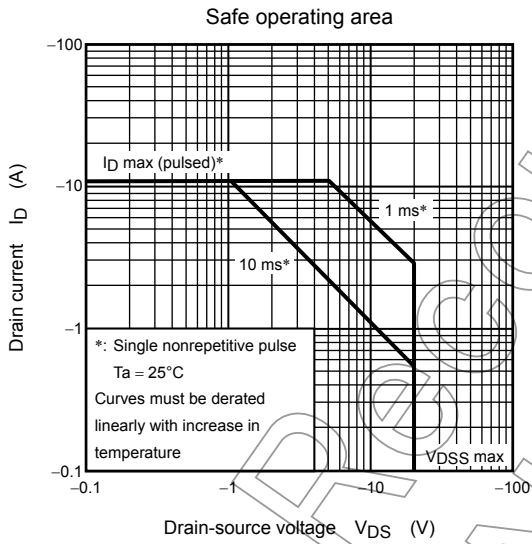
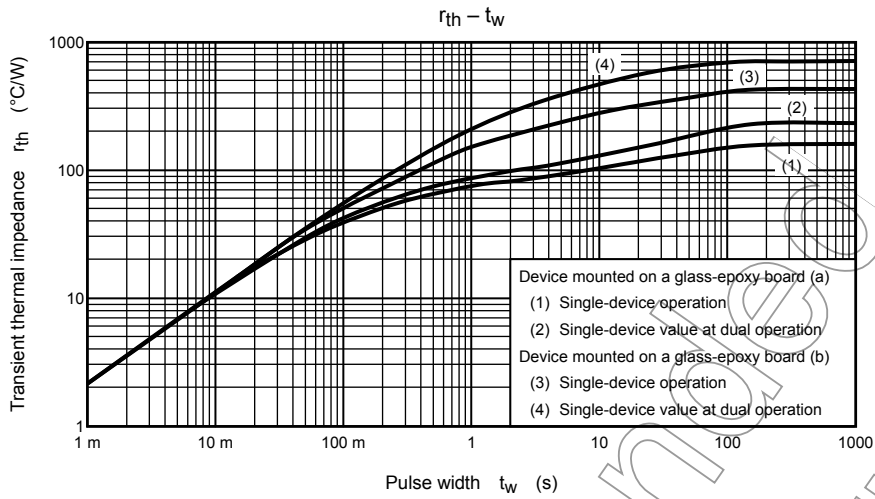
Note 5: Repetitive rating: Pulse width limited by maximum channel temperature.

Note 6: A dot on the lower left of the marking indicates Pin 1

Not for







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